

Features

- Excellent thermal conductivity
- Excellent insulating ability
- Excellent Dimensional Stability
- Excellent Mechanical Strength
- Lower heat expansibility
- Lower operating temperature
- Increase power density
- Reduce the number of interconnects
- Extend the life of dies

Star-LG3535-MCPCB

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ALUMINUM CLAD PRINTED

CIRCUIT BOARD FOR

LG3535

ALLOWS OPTIMUM HEAT

DISSIPATION

This is a custom MCPCB structure that further enhances heat dissipation thus enabling the LED to last according to its life time.

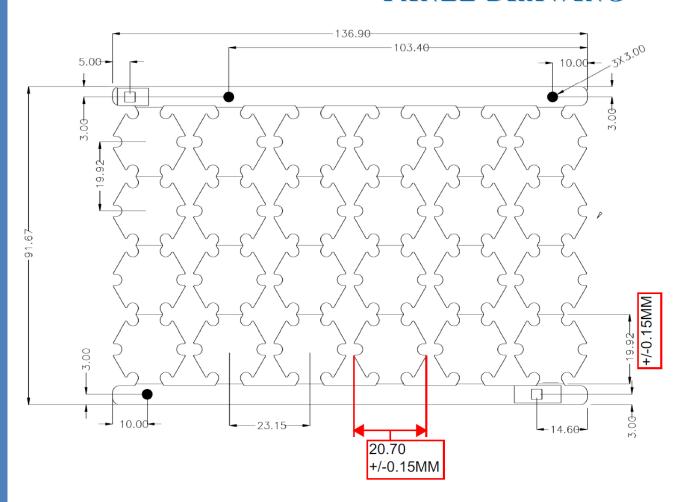
Higher thermal conductive MCPCB is also available with our special enhanced capabilities.

CONSTRUCTION OF MCPCB

The structure of the aluminum material includes copper layer, dielectric layer laminated together with aluminum base layer. Below appends summary of available range of material:

Aluminum	Aluminum	Copper	Dielectric
Type	Thickness	Thickness	Thickness
AL 5052	1.5 mm	1 oz	100um

PANEL DRAWING



MATERIAL DATASHEET

Material data sheet - OP-AL (OPT111g.01.Al5215.4.0018)

				-	
Items	Method description	Treatment Condition	Specification	Typical Value	Unit
Thermal Properties					
Thermal Resistance (Dielectric layer)	Calculation from ASTM D5470	A [2]	≤ 0.62	0.56	°C-cm²/W
Thermal Conductivity (Dielectric layer)	Extended ASTM D5470	A ^[2]	≥ 1.62	1.8	W/m-k
Maximum Operating Temperature (MOT)	UL 746 E	_	-	125	°C
Glass Transition Temp (Tg, DSC)	IPC-TM-650 2.4.25	A [2]	-	100	°C
Coefficient of Thermal Expansion (CTE)	IPC-TM-650 2.4.24	A [2]	-	37	x10 ⁻⁶ /°C
		30°C~260°C			
Electrical Properties					
Dielectric constant	IPC-TM-650 2.5.5.9	1MHz	-	5.2	-
Dissipation Factor	IPC-TM-650 2.5.5.9	1MHz	-	0.029	_
Volume Resistivity	IPC-TM-650 2.5.17.1	C-96/35/90 [1]	≥ 1×10 ⁶	1×10 ⁷	MΩ·cm
Surface Resistivity	IPC-TM-650 2.5.17.1	C-96/35/90 [1]	≥ 1×10 ⁴	1×10 ⁵	МΩ
Dielectric Breakdown Voltage	IPC-TM-650 2.5.6.2	-	-	≥ 30	kvAC/ mm
PCB high pot withstand	IPC-TM-650 2.5.7	-	-	≥ 30 [4]	kvDC/ mm
Mechanical Properties					
Dielectric Thickness	Optical	A [2]	-	100	μm
Peel Strength	IPC-TM-650 2.4.8	A ^[2] 288°C.10S	≥ 1.05	1.70	N/mm
Chemical Properties					
Water absorption	IPC-TM-650 2.6.2.1	D-24/23 ^[3]	≤ 0.8	0.06	%
Ratings and Durability					
UL Flammability	UL94	-	-	94 V-0	-
Comparative Tracking Index (CTI)	IEC60112	-	-	>= 600	٧
Thermal stress	IPC-TM-650 2.4.13.1	288 °C	≥ 30S (No delamination, no blister)	≥ 30S (No delamination, no blister)	-

^{*} Non-mentioned PCB information based on: Aluminium thk 1.5mm, Al type 5052; Copper foil 1oz

^{* 1 -} Humidity conditioning (90%) at 35 deg C, duration 96H; 2 - As received

I - Immersion conditioning (300) at 30 sept. detailed in the sept. At 30 sept. Circuit design is the most important consideration for determining safety agency compliance.

^{*} For applications with an expected voltage over 400VAC (or 500VDC), Opulent recommends a dielectric thickness not less than 0.004" (100µm).

^{*} Our company reserves the right to future changes. It is the responsibility of the user to ensure that the product complies with his requirements.



PRODUCT SPECIFICATIONS

Star-LG3535- MCPCB

Aluminum Type: AL5052

Aluminum Thickness: 1.5mm

Copper Thickness: 1oz

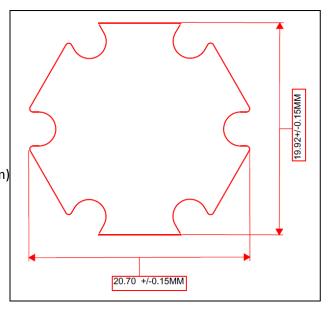
Dielectric Thickness: 100um

Unit Size: 20.70mm x 19.92mm (±0.15mm)

Panel Size: 136.9 x 91.68mm (24pcs/pnl)

Finishing: OSP

Solder Mask: Matte Black



SOLDER PASTE

Type: Lead-free SAC 305 paste, grade 3 or above

Lumileds Internal: Alpha Metal OM325 grade 4

Alternative: Alpha Metal OM338 grade 3

PACKAGING

One carton consists of 10 internal white boxes. Each white box consists of 3 trays. Each tray consists of 48 pieces.

Type of tray: Individual slot for each Star-LG3535-MCPCB

Cavity per tray: 48 pcs

Dimension of tray: 443 x 173cm x 22mm

Internal White Box: contains 3 trays with 1 cover tray (equivalent to 144pcs of Star-LG3535-

MCPCB)

Dimension of I.W.B: 445 x 180 x 55mm

Carton box: contains 10 white boxes (equivalent to 1440pcs of OP Star-LG3535-MCPCB)

Dimension of carton: 470 x 375 x 300mm



ABOUT OPULENT

Opulent (Asia)

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eadquartered in Singapore, Opulent has more than 20 years experience in the manufacturing of conventional printed circuit boards (PCBs). Embarking for an international presence, Opulent has set up sales and marketing support in China, Hong Kong, Germany, Italy, United Kingdom and Malaysia.

Through innovation and R&D, Opulent created metal-clad PCBs (MCPCB) and is currently a leading designer and manufacturer of thermal solutions. Our products and works are guided by a customer centric approach that empowers us to provide value added solutions from design to assembly.

Our customers are well-known international brands whom have come to trust Opulent for our innovation, our knowledge and our commitment to attain customer satisfaction.

